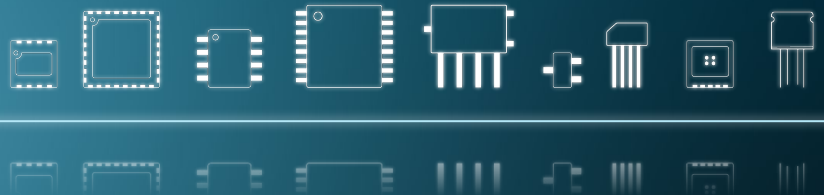


# First Quarter 2026 Results



# What do we do?

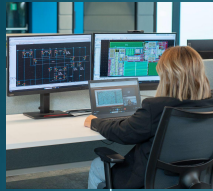
Melexis engineers microelectronic solutions. Our technology makes cars and other products smarter, safer and greener. Our sensors capture data from the analog world and comprehend these data digitally. Our drivers make sure customers can bring their products to life.

# From idea to solution

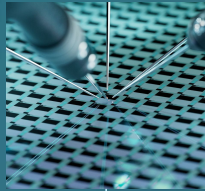
Define



Design and layout



Wafer probe



Final test



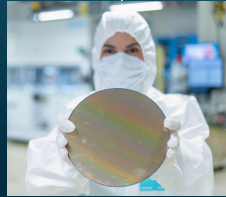
Chips



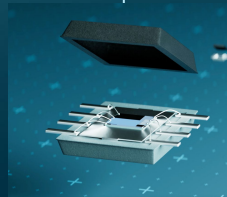
What we do

External

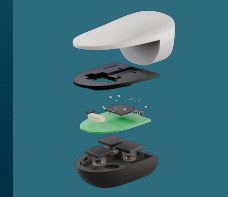
350-110 nm (8")  
130 nm (8")  
90 nm (12")  
40 nm (12")



Wafer fab




IC assembly



Module assembly



Full solutions



**3** continents  
**20** locations

### **Sales & Applications**

Belgium – Ieper, Tessenderlo  
Greater China – Shanghai, Shenzhen, Taipei  
France – Sophia Antipolis, Paris  
Germany – Erfurt, Dresden  
Japan – Yokohama  
South Korea – Seoul  
Switzerland – Bevaix  
United States – Novi  
United States – San Jose

### **Manufacturing**

Belgium – Ieper  
Bulgaria – Sofia  
France – Corbeil-Essonnes  
Germany – Erfurt  
Malaysia – Kuching

### **Research & Development**

Belgium – Ieper, Tessenderlo  
Bulgaria – Sofia  
France – Sophia Antipolis, Paris  
Germany – Erfurt, Dresden, Düsseldorf  
Malaysia – Kuching  
Philippines – Manila  
Switzerland – Bevaix  
Ukraine – Kyiv

# Markets



AUTOMOTIVE



ALTERNATIVE MOBILITY



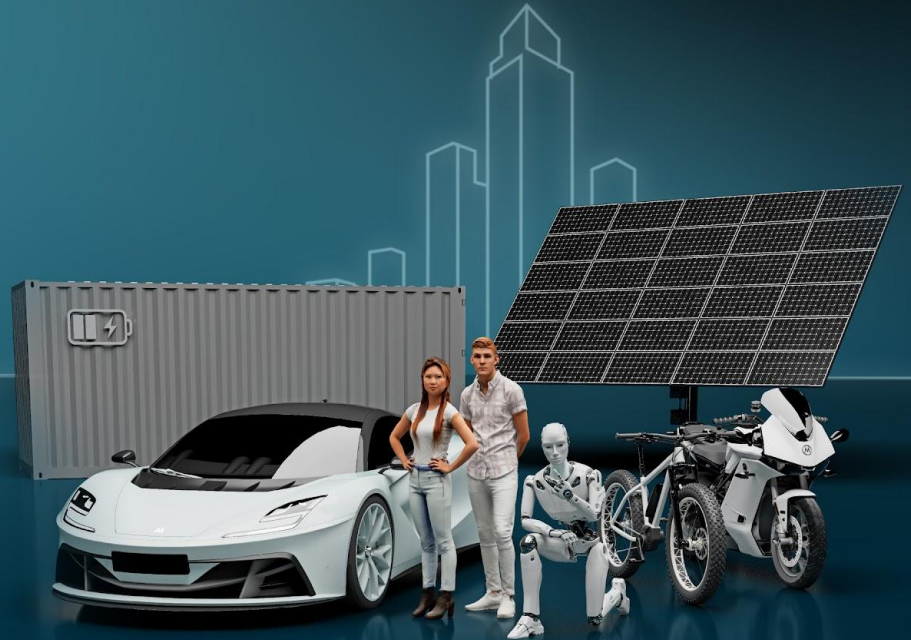
SUSTAINABLE WORLD



ROBOTICS



DIGITAL HEALTH



Automotive

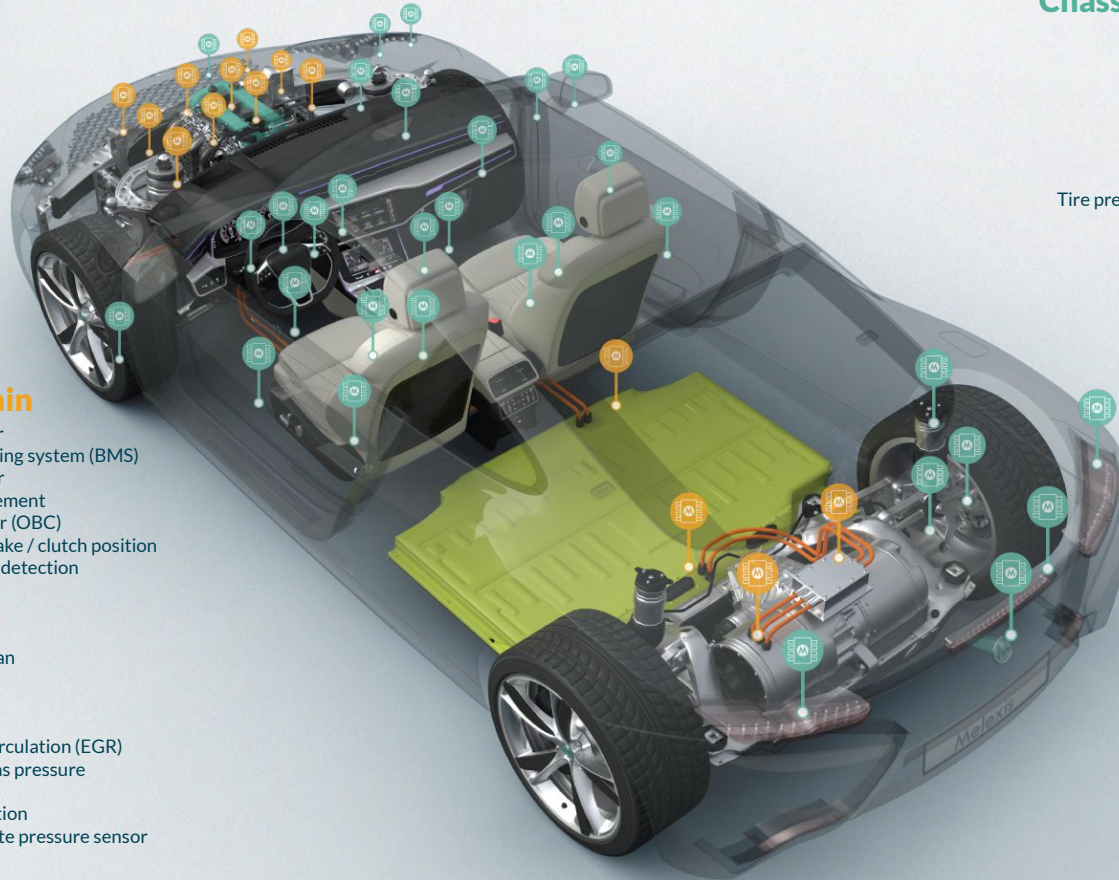


# Melexis chips in every new car



## Powertrain

- Traction inverter
- Battery monitoring system (BMS)
- DCDC converter
- Thermal management
- Onboard charger (OBC)
- Accelerator / brake / clutch position
- Brake fluid level detection
- Transmission
- Clutch switch
- Gear shift
- Engine cooling fan
- Water pump
- Water valves
- Grille shutter
- Exhaust gas recirculation (EGR)
- Valve exhaust gas pressure
- Throttle
- Crankshaft position
- Manifold absolute pressure sensor
- Fuel pump
- Fuel level



## Chassis - Body - Safety



- ADAS / Dashboard GPU cooling
- Washing liquid level detection
- Wiper
- Rain-light sensor
- Hood lock switch
- LED headlight ventilation fan
- LED and laser headlight control
- Tire pressure monitoring system (TPMS)
- Smart tire sensor
- Ride height
- Electrical power steering (EPS)
- Brake light switch
- Turn signals / stalk-end position
- Electric parking brake
- Flap position detection
- Climate control / HVAC
- Seat heating and ventilation
- Seat belt buckle
- Seat position adjuster
- Seat lumbar pressure
- Keyless entry
- Door lock switch
- Door handle wake up switch
- Side mirror adjuster
- Window lift
- Sunroof
- In-vehicle networking
- Interior ambient lighting
- Interior animated lighting
- Puddle lights
- Stop lights
- Rear lights
- Tailgate/trunk motor opener
- Trunk lock switch

# Major automotive trends

## Electrification

- EV powertrain
- Thermal management
- Battery
- Power management

## Premiumization

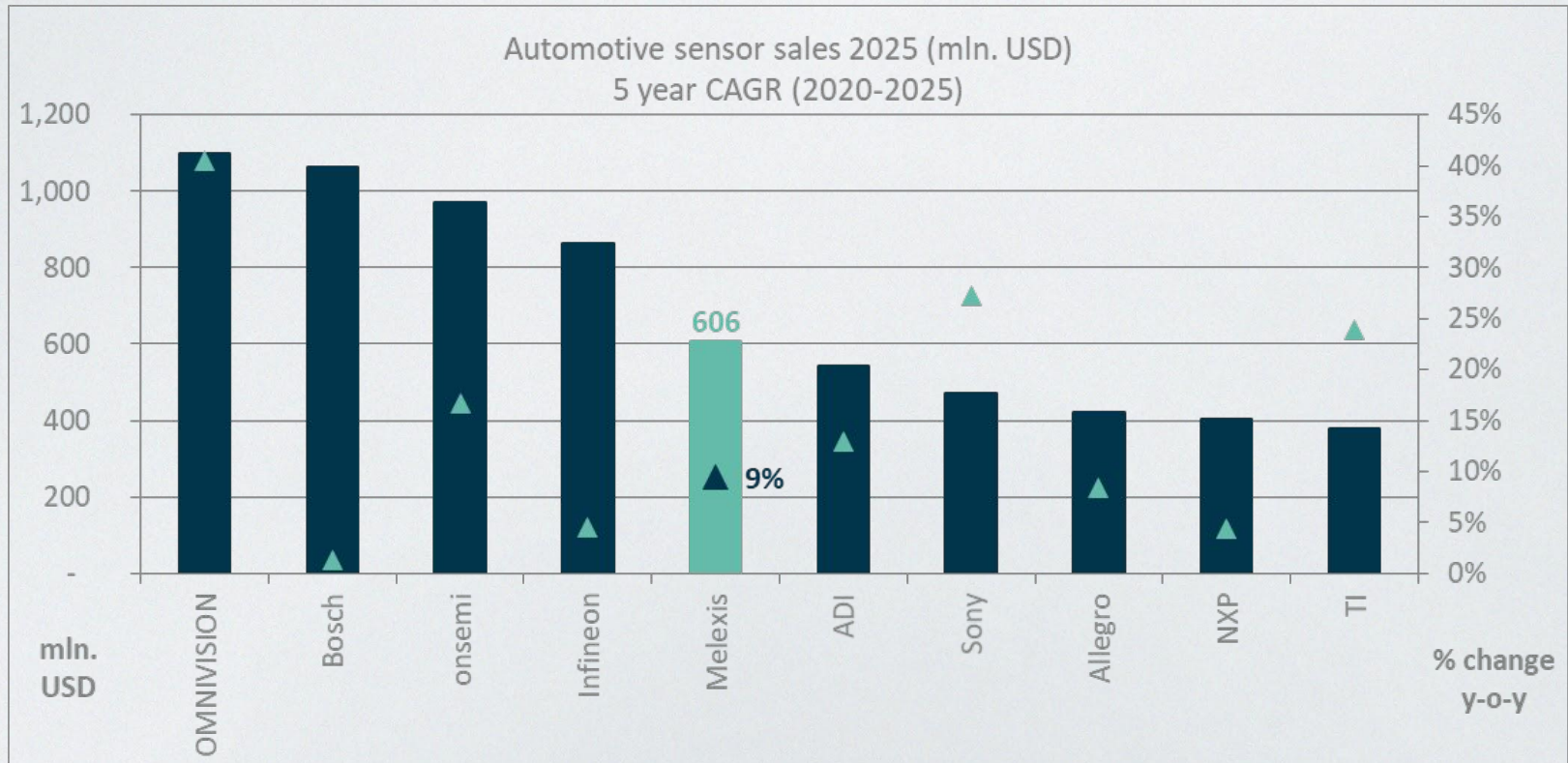
- Interior and exterior lighting
- Motors (seat, window, HVAC, grille shutter)

## ADAS

- E-braking and E-steering
- Dynamic lighting
- TPMS

Melexis has a well diversified portfolio, limiting its dependency on the type of powertrain.

# Melexis ranks 5<sup>th</sup> worldwide in automotive sensors



# Technology leadership

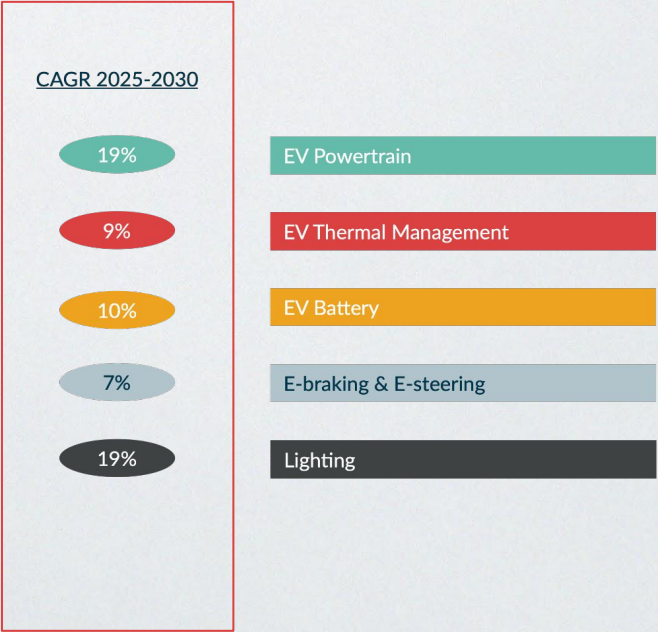
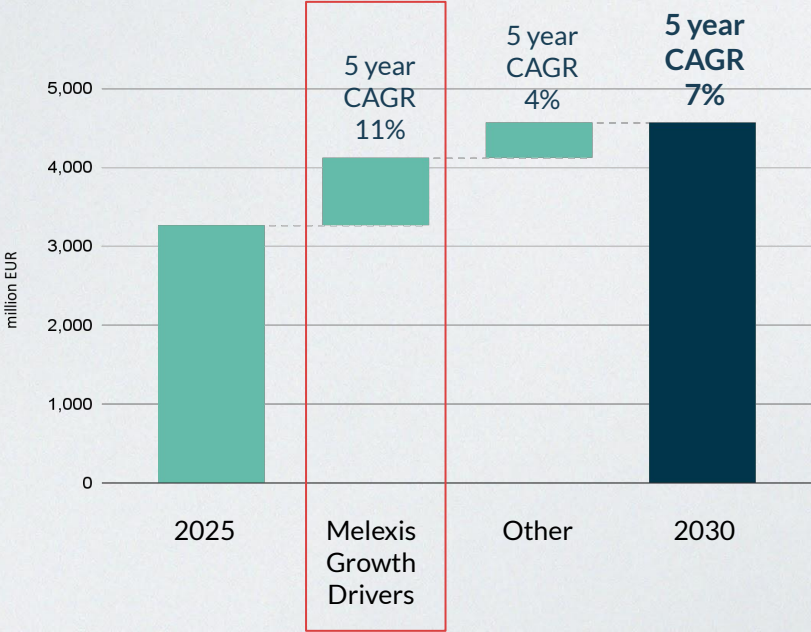
## Automotive Growth Drivers

<b>Steering &amp; Braking</b> Sensors	<b>EV Powertrain</b> Sensors	<b>Thermal management</b> Sensors	<b>Thermal management</b> Drivers	<b>Interior Lighting</b> Drivers
<b>1 Melexis</b> 2 Infineon 3. Allegro	<b>1. Melexis</b> 2. Allegro 3. Novosense	<b>1. Melexis</b> 2. TDK 3. Allegro	<b>1. Melexis</b> 2. Elmos 3. TDK	<b>1. Melexis</b> 2. Indie 3. Elmos

400+ patents  
Average of 40 patent families per year

# Melexis: Automotive Service Addressable Market

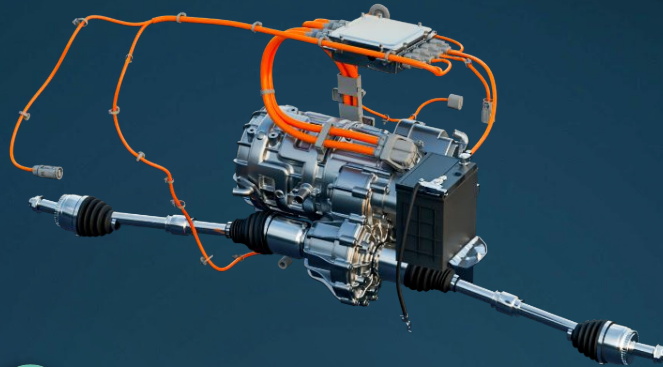
Growth Drivers outperform with 11% revenue CAGR



Source: Melexis management estimates for 2025 and 2030 based on bottom-up sockets model.

# EV powertrain

- AC phase current monitoring
- Rotor position sensing
- Power module temperature monitoring
- Safety cover open/close detection
- Boosting power module performance



current  
sensor IC



temperature  
sensor IC



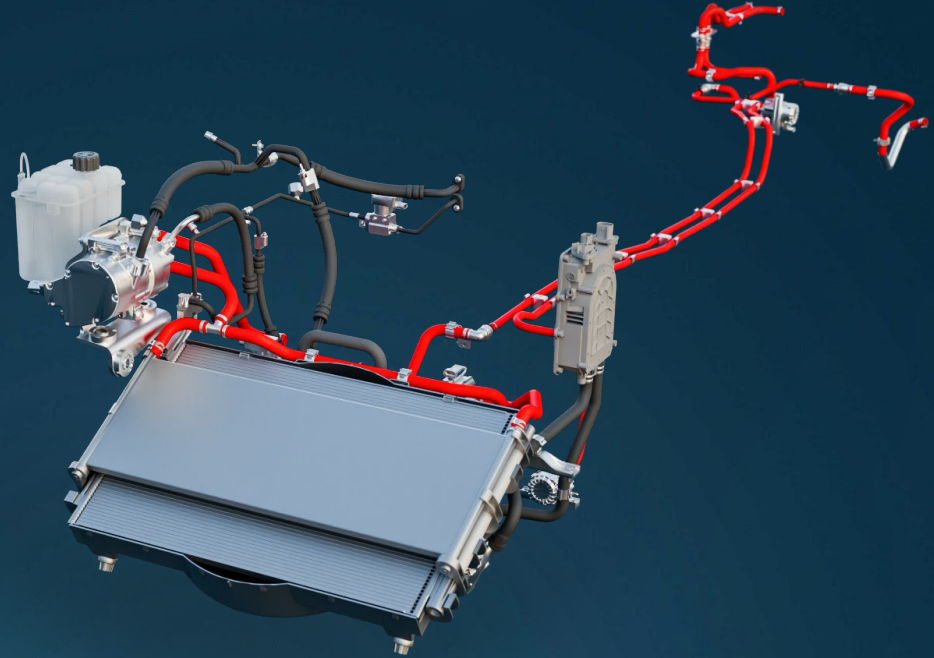
position  
sensor IC



latch &  
switch IC

# EV thermal management

- Pressure & temperature monitoring
- E-compressor current sensing
- Fast charge current monitoring
- Valve & pump positioning & controlling
- Refrigerant pressure sensing



position  
sensor IC



current  
sensor IC



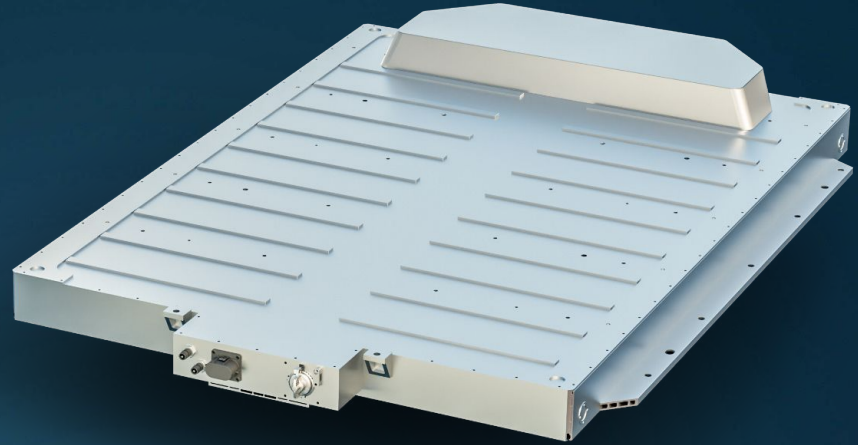
pressure  
sensor IC



motor  
driver IC

# EV battery

- AC & DC current monitoring
- Pack & cell level pressure monitoring
- Contactless temperature monitoring
- Hydrogen sensing
- Cell level voltage, temperature and impedance monitoring



pressure  
sensor IC



temperature  
sensor IC



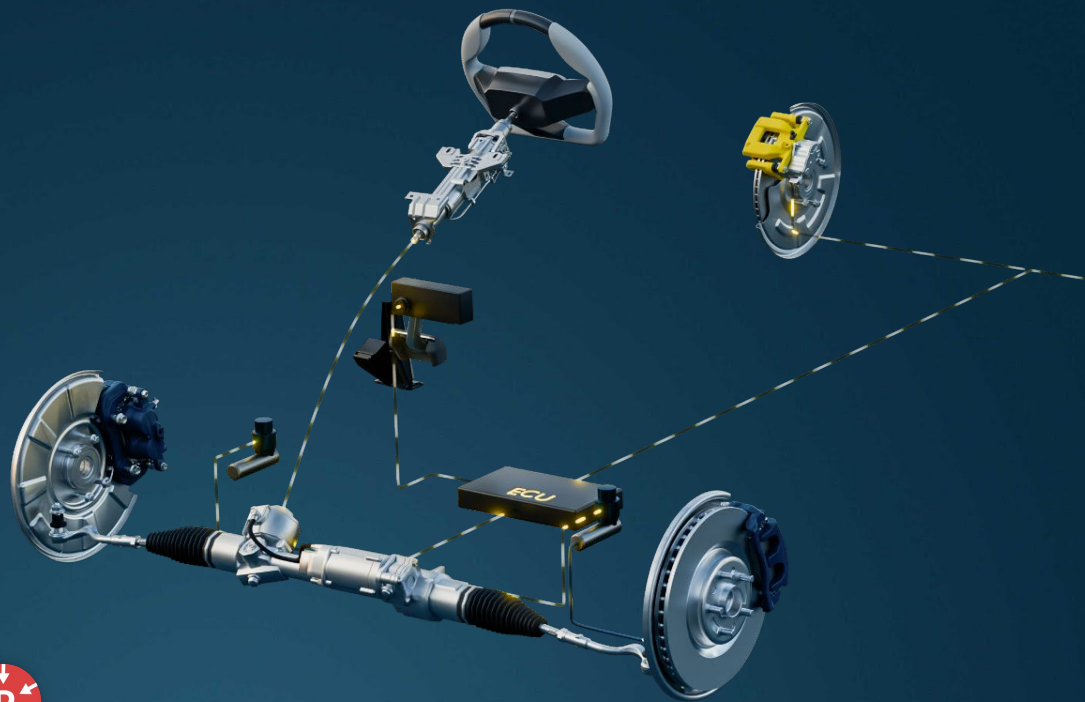
current  
sensor IC



sensor  
interface IC

# E-braking & E-steering

- Wheel angle position & torque sensing
- Pedal position sensing
- Caliper position & force sensing
- Rotor positioning
- Park lock motor positioning & controlling



sensor  
interface IC



position  
sensor IC



latch &  
switch IC



motor  
driver IC



pressure  
sensor IC

# Lighting

- Interior ambient lighting
- Animated lighting
- Logo & grille illumination
- Daytime running light
- Rear lighting



LED  
driver IC

# Robotics require many sensors and drivers

- Joints
  - Position sensors
  - Compact Motor drivers
  - Torque sensors
- Battery management
  - Thermal sensing
  - Current sensing
- Power train (2-, 3-, 4-wheels)
  - Motor drivers
- End effectors
  - Force sensors
  - Thermal sensors
- Environment sensing
  - Thermal sensors
- Complex embedded SW (Edge AI)



Industrial robot



Service robot



Humanoid robot



Service robot



latch & switch IC



position sensor IC



current sensor IC



motor driver IC

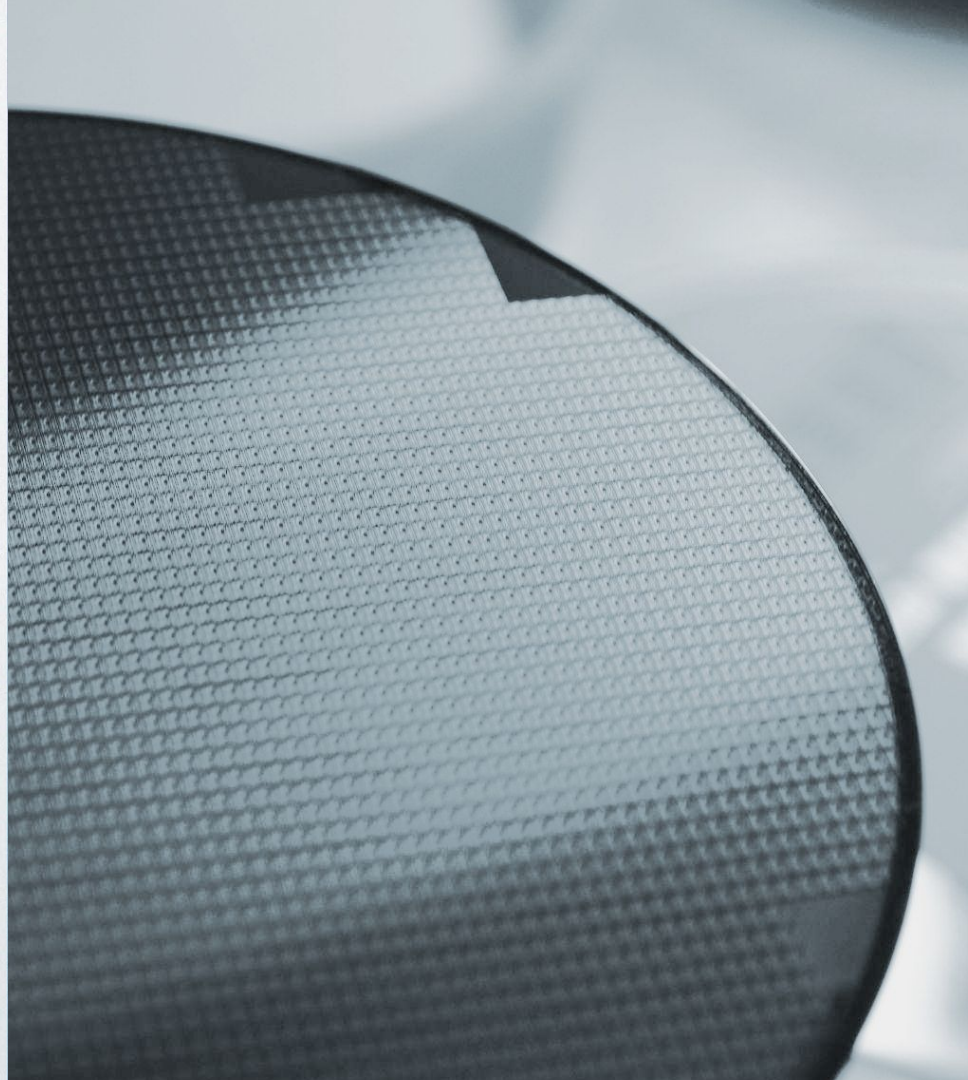


temperature sensor IC

# End-to-end China Strategy

## 端到端的中国战略

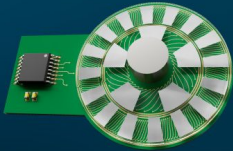
- Local outsourced semiconductor assembly and test (OSAT) partner  
外包半导体封装测试合作伙伴
- Chinese semiconductor wafer fabrication partner  
中国晶圆制造合作伙伴
- Locally embedded logistics hub  
本地物流中心



# Melexis is at the forefront of innovation

## INDUCTIVE POSITION SENSOR ICs

22-bit dual input encoder  
with on-chip Vernier angle



MLX90520

- Rotary (360°) or Linear (<40cm)
- Dual-channel operation with zero latency
- Compact coil design and tighter PCB Layouts



## EMBEDDED MOTOR DRIVER ICs

Silent 3-phase fans driver  
without coding



MLX80339

- Accelerate time-to-market
- Superior efficiency & acoustics
- Robust integration (<40 W)
- Easy GUI-based configuration

<Code Free>

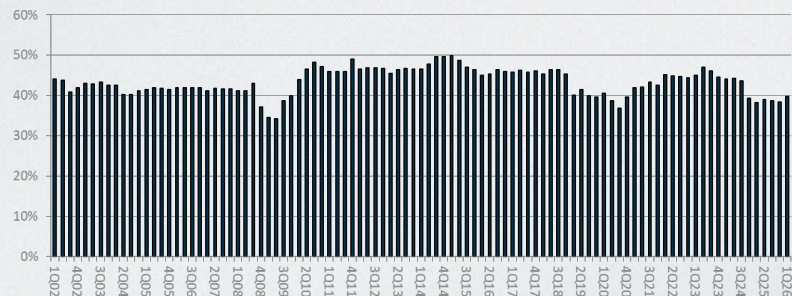


# Evolution Financials 2002-2026

## Gross result

Q1 2026: 80.6 mln EUR (39.9%)

FY 2025: 324.0 mln EUR (38.6%)



## Turnover

Q1 2026: 202.1 mln EUR

FY 2025: 839.6 mln EUR



## Operating result

Q1 2026: 33.2 mln EUR (16.4%)

FY 2025: 134.0 mln EUR (16.0%)



# Q1 2026 results at a glance

<b>Sales</b> 202.1 mln EUR +2% Y-o-Y	<b>Gross margin</b> 39.9% 80.6 mln EUR +7% Y-o-Y	<b>Operating result</b> 16.4% 33.2 mln EUR +14% Y-o-Y
<b>Net result</b> 0.57 EPS 23.1 mln EUR -6% Y-o-Y	<b>Operating cash flow</b> (before working capital changes) 43.8 mln EUR +1% Y-o-Y	<b>Net debt</b> 207.0 mln EUR

## Outlook

Melexis confirms its outlook, and expects sales in the first half of 2026 to be around the same level as the previous year.

Sales in the second half of 2026 are expected to grow compared to the first half of 2026.

For the first half of 2026, Melexis expects a gross profit margin around 40% and an operating margin around 17%, all taking into account a EUR/USD exchange rate of 1.17.

For the full year 2026, Melexis expects CAPEX to be around 40 million EUR.

# Profit & loss

Q1 2026 versus Q1 2025 versus Q4 2025

P&L account (in million EUR)	Q1 2026	% of Sales	Q1 2025	% of Sales	Q4 2025	% of Sales
<b>Sales</b>	202.1	100.0%	198.2	100.0%	214.5	100.0%
Cost of goods sold	-121.5	-60.1%	-122.6	-61.8%	-132.2	-61.6%
<b>Gross margin</b>	80.6	39.9%	75.7	38.2%	82.3	38.4%
R&D	-29.3	-14.5%	-28.4	-14.3%	-31.1	-14.5%
G&A	-13.7	-6.8%	-13.5	-6.8%	-14.4	-6.7%
Selling	-4.4	-2.2%	-4.8	-2.4%	-5.3	-2.5%
<b>EBIT</b>	33.2	16.4%	29.0	14.6%	31.5	14.7%
Net financial result	-4.3	-2.1%	-0.5	-0.2%	-3.0	-1.4%
Income taxes	-5.8	-2.9%	-3.9	-2.0%	-5.9	-2.8%
<b>Net profit</b>	23.1	11.4%	24.6	12.4%	22.6	10.5%
<b>Earnings per share</b>	0.57		0.61		0.56	

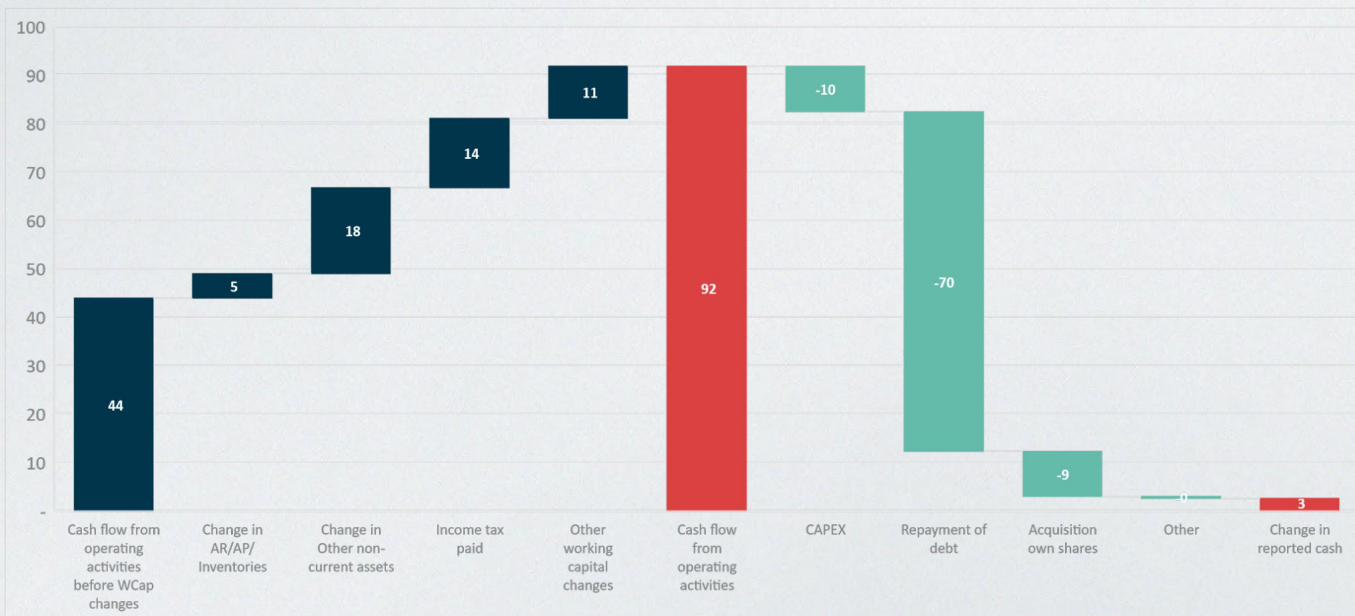
# Balance Sheet

Q1 2026 versus Q1 2025 versus Q4 2025

Balance Sheet (in million EUR)	Q1 2026	Q1 2025	Q4 2025
<b>Total assets</b>	851.2	904.9	903.3
<b>Current assets</b>			
Cash	37.1	34.8	34.6
Inventory	292.2	281.8	300.3
A/R Trade	105.5	101.6	107.9
<b>Non-current assets</b>	303.8	396.2	323.9
<b>Shareholders' equity</b>	499.1	576.2	484.5
<b>Interest bearing debt</b>	314.3	217.7	314.3
Long term	233.5	205.4	301.3
Short term	10.7	12.3	13.0

# Q1 2026 cash flow

Mln. EUR



Free cash flow of  
82 mln EUR

Repayment of debt for a  
total of 70 mln EUR

# Melexis target operating model

Outperform our markets through innovation and profit growth through the cycle

Sales

high single digit  
CAGR

Gross margin

45%

EBIT margin

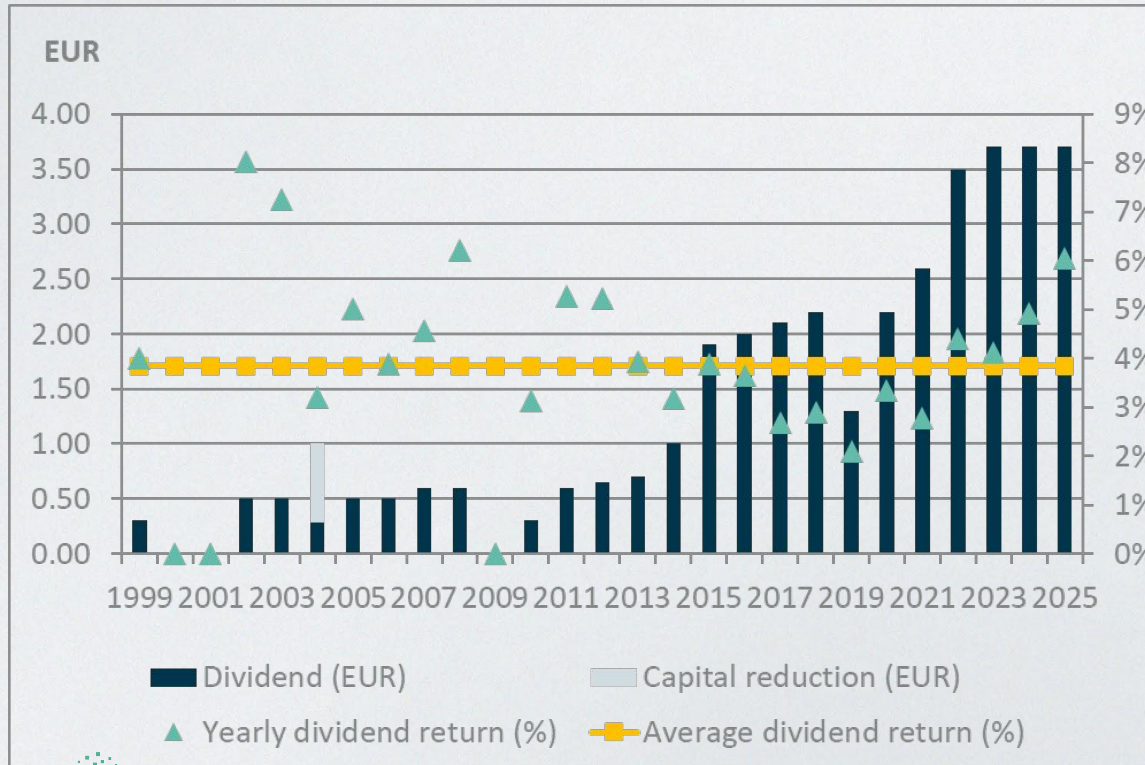
25%

## Key assumptions

- Outperform where we play (SAM: 7% automotive, higher in multi-markets)
- Volume assumptions: automotive production stable, unit growth in multi-markets, overall content growth (value of chips per unit), high multipliers in multi-markets
- Focus on Melexis growth drivers in multiple markets
- Higher ASPs through increasing system solutions

# Cash return to shareholders

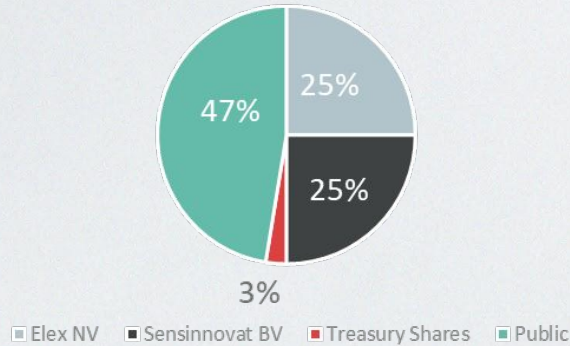
Yield based on average share price



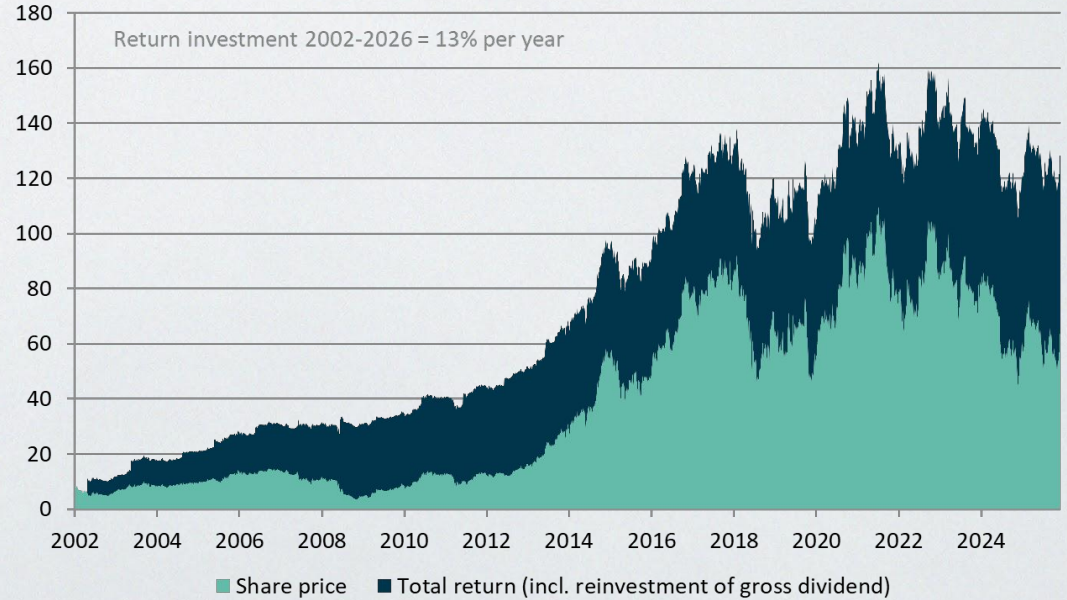
- Solid dividend yield and long track record
- Share buy-back program for up to 850 thousand shares for an amount of up to EUR 50 million renewed in December 2025

# Shareholder structure and shareholder return

Shareholder structure on  
31 March 2026



Shareholder Return  
2002-2026



# INDUSTRY FIRST

## 1996

Programmable linear Hall sensor



## 2001

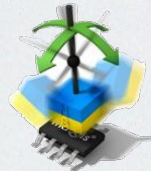
LIN system basis chip

## 2004

Single chip smart LIN

## 2005

Triaxis® magnetic sensor



## 2007

Integrated infrared thermometer (FIR)

## 2010

Single chip sensor-less BLDC motor drive solution

## 2011

- Fully integrated passive entry automotive qualified NFC
- 3D camera sensor

## 2012



- Single chip LIN RGB driver
- SENT pressure sensor
- 16x4 infrared array

## 2013

- Programmable Hall sensor for high performance current sensing
- End-of-line programmable Hall latches

## 2014



- WPC & NFC automotive solution
- Programmable 2-wire Hall sensor with integrated capacitor
- Triaxis® micropower magnetometer for automotive
- Time-of-flight 3D camera IC

## 2015

Thermocouple Interface with on-board diagnostic featuring SENT

## 2016

- Smallest Tire Pressure Monitoring Sensor (TPMS) IC
- Far Infrared Thermal (IR) sensor array

## 2017

- Time-of-flight chipset
- Dual die L&S sensor

## 2018

- ASIL ready Triaxis® Position sensor IC
- Hall-effect current sensors

## 2019



- Automotive grade single-chip VGA time-of-flight sensor
- Miniature medical grade infrared temperature sensor

## 2020

Multi-channel RGB-LED driver enabling high-speed light animations (MeLiBu®)

## 2021

Synthesize inductive resolver

## 2022



- Tactaxis™ gives robot a sense of touch
- Revolutionary floating switch
- Pico-resolver
- Most accurate automotive pressure sensor IC ever made
- Dual quadrature outputs L&S
- Triaxis® PCB-less dual stack dies

## 2023

- First contactless temperature to be integrated in a smartwatch.
- Accurate Hall-Effect DC current sensor IC

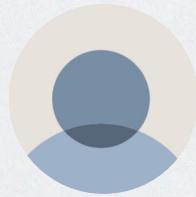
## 2024

- Triphibian MEMS pressure sensor for gas and liquid media from 2 to 70 bar
- Induxis® inductive switch with integrated coils

## 2025

- Automotive driver supporting up to 500 RGB LEDs (MeLiBu®) allowing more differentiated offerings

# Melexis Investor Relations



Philip Ludwig  
Investor Relations

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